

Metafoam Technologies Will Participate in MetFoam 2007 Conference

Montreal, August 17th, 2007

Metafoam[®] Technologies is pleased to join the exhibitors and lecturers of MetFoam 2007, the 5th international conference on metal foams and other porous materials.

Attendees are invited to Metafoam's booth and to take part in the presentation "Characterization of High Surface Area Open-Cell Metal Foams and Application to Thermal Management and Electrochemistry" presented by the Founder and Chief Technology Officer of the Company, Mr. Dominic Pilon.

MetFoam is the largest conference for engineers and product designers seeking materials having unique combination of properties as well as for researchers interested in latest developments in porous metals. MetFoam will take place in Montreal, Canada from September 5th to 7th, 2007.

About Metafoam

Metafoam Technologies Inc. is specialized in the development and commercialization of innovative open-cell metal foam solutions. Metafoam is revolutionizing the open-cell metal foam industry by offering the highest specific surface area and greater control on several key product parameters. As such, Metafoam is exceptionally positioned to address a wide range of needs, namely in electronics cooling and electrochemistry.